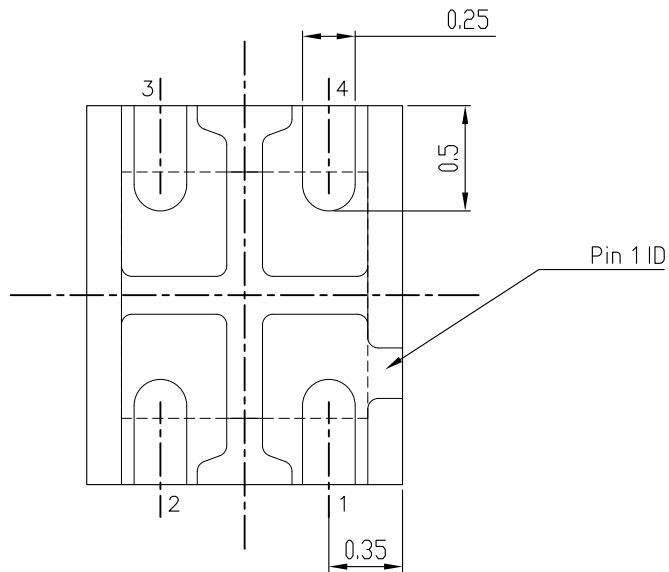


Pin Assignments	
Pin #	Description
1	Anode
2	Fast Output
3	Cathode
4	No Connect

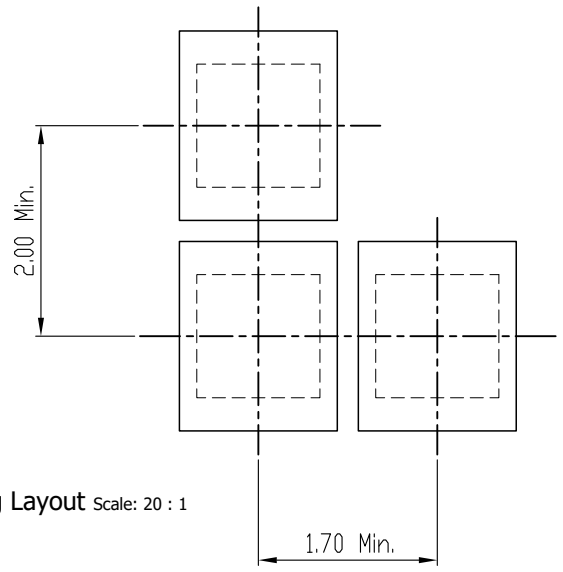
DATE	19 July 2017	REVISION	A	SCALE:	Shown
SensL Technologies Ltd					Sheet
www.sensl.com					1 of 6
DWG. NO:	SNDO218	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroRA-100XX-MLP-C1					
PROJECTION:					



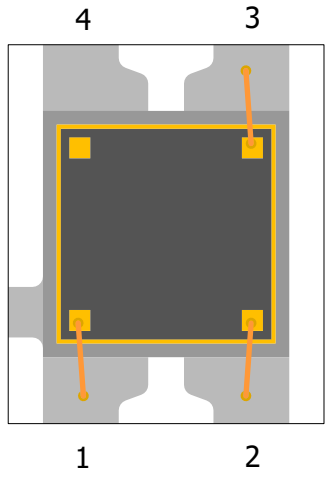
Bottom View Scale: 40 : 1

Pin Assignments	
Pin #	Description
1	Anode
2	Fast Output
3	Cathode
4	No Connect

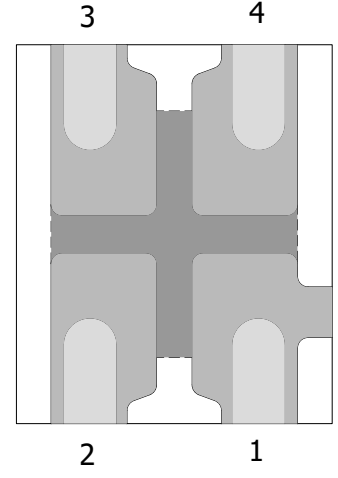
DATE	19 July 2017	REVISION	A	SCALE:	Shown
SensL Technologies Ltd				Sheet	
www.sensl.com				2 of 6	
DWG. NO:	SNDO218	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroRA-100XX-MLP-C1					
PROJECTION:					



Tiling Layout Scale: 20 : 1



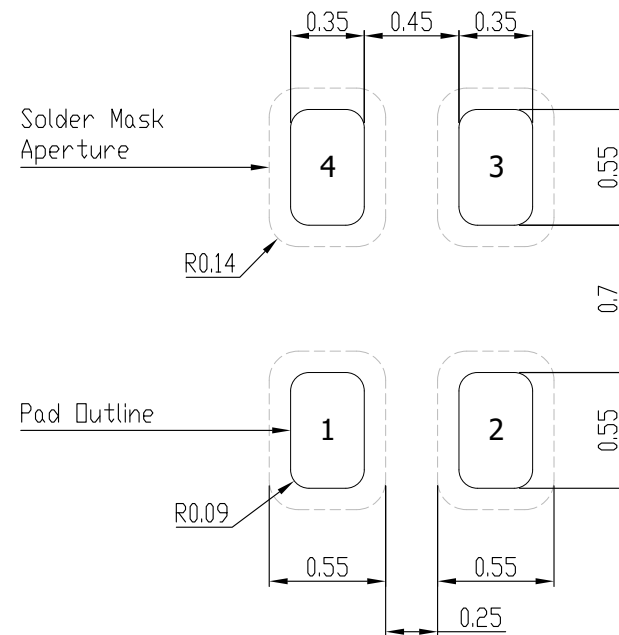
Top View Scale: 40 : 1



Bottom View Scale: 40 : 1

NOTE: Alignment and placement tolerances depend on the accuracy of the equipment used in the assembly process.

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SensL Technologies Ltd				Sheet 3 of 6	
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DWG. NO:	SN00218	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroRA-100XX-MLP-C1					
PROJECTION:					

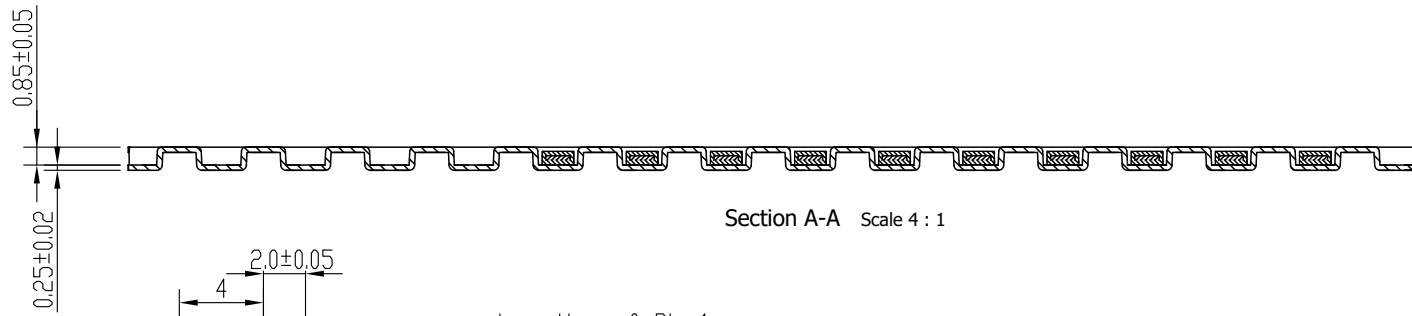


Recommended PCB Solder Footprint

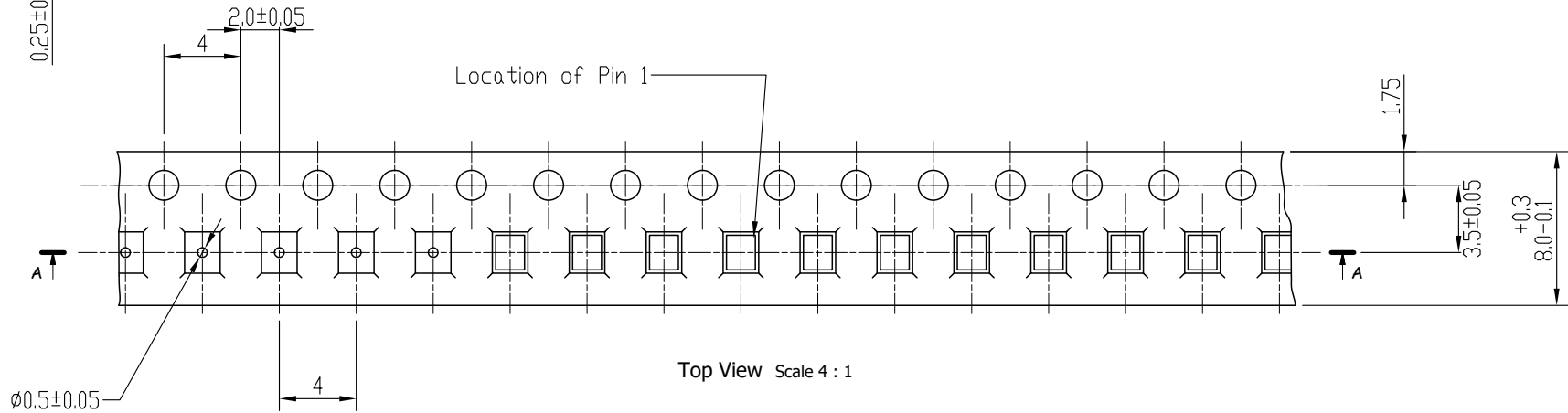
Scale: 40 : 1

NOTE: No Connect (NC) pin 4 should be soldered to PCB, this pin can be connected to ground but it can also be left floating without affecting the dark noise.

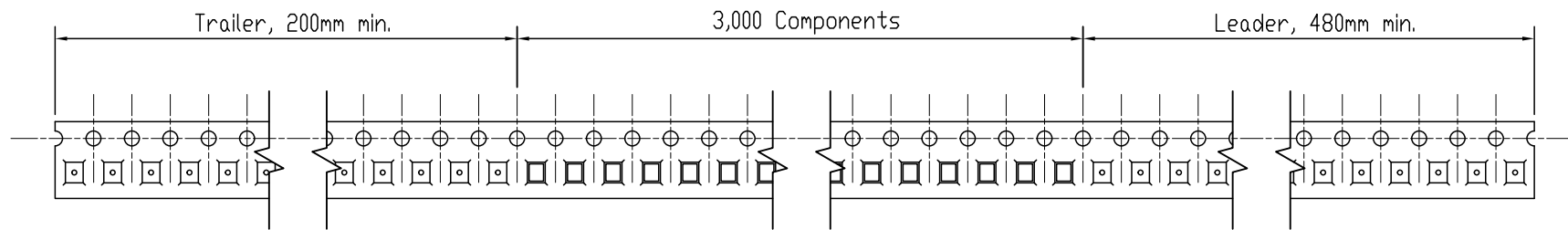
DATE	19 July 2017	REVISION	A	SCALE	Shown
SensL Technologies Ltd				Sheet 4 of 6	
www.sensl.com					
DWG. NO:	SND0218	DO NOT SCALE ALL DIMENSIONS IN MM			
TITLE: <b>MicroRA-100XX-MLP-C1</b>					
PROJECTION:					



Section A-A Scale 4 : 1



Top View Scale 4 : 1

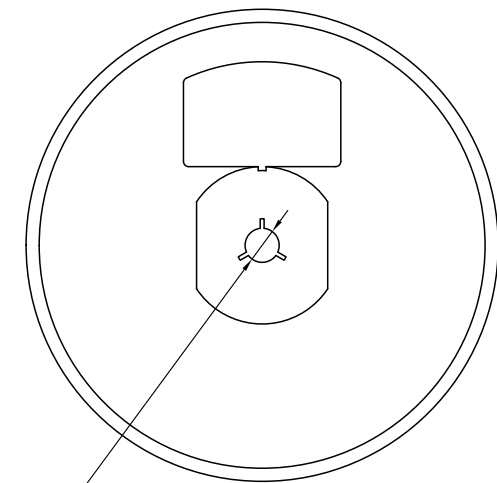


Customer Feed Direction →

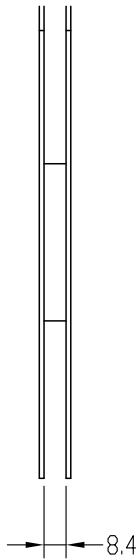
Tape Feed Scale 2 : 1

All Dimensions ± 0.1mm Unless Otherwise Stated

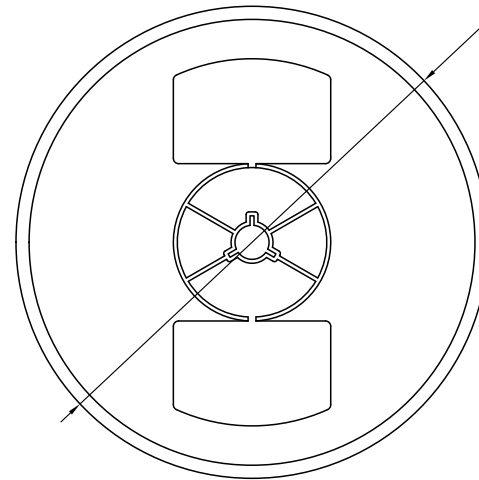
DATE	19 July 2017	REVISION	A	SCALE	Shown
SensL Technologies Ltd				Sheet 5 of 6	
www.sensl.com					
DWG. NO:	SND0218	DO NOT SCALE ALL DIMENSIONS IN MM			
TITLE:					
MicroRA-100XX-MLP-C1					
PROJECTION:					



Ø13.0



Ø180.0



Details of Packaging Reel Scale 1 : 2

	<b>CAUTION</b>	<b>3</b>
<b>MOISTURE SENSITIVE DEVICES</b>		
1. Calculated shelf life in sealed bag: 24 months at <math>+40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH)		
2. Peak package body temperature: <b>260</b> °C If blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <b>168</b> hours of factory conditions <math><30^{\circ}\text{C}/60\%</math> RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads <math><10\%</math> for level 2a - 5a devices or <math>>80\%</math> for level 2 devices when read at <math>23 \pm 5^{\circ}\text{C}</math>		
b) 5a or 5b are not met.		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <b>20 Mar. 2014</b> If blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

Details of Moisture Sensitivity Label

Moisture Sensitivity Label

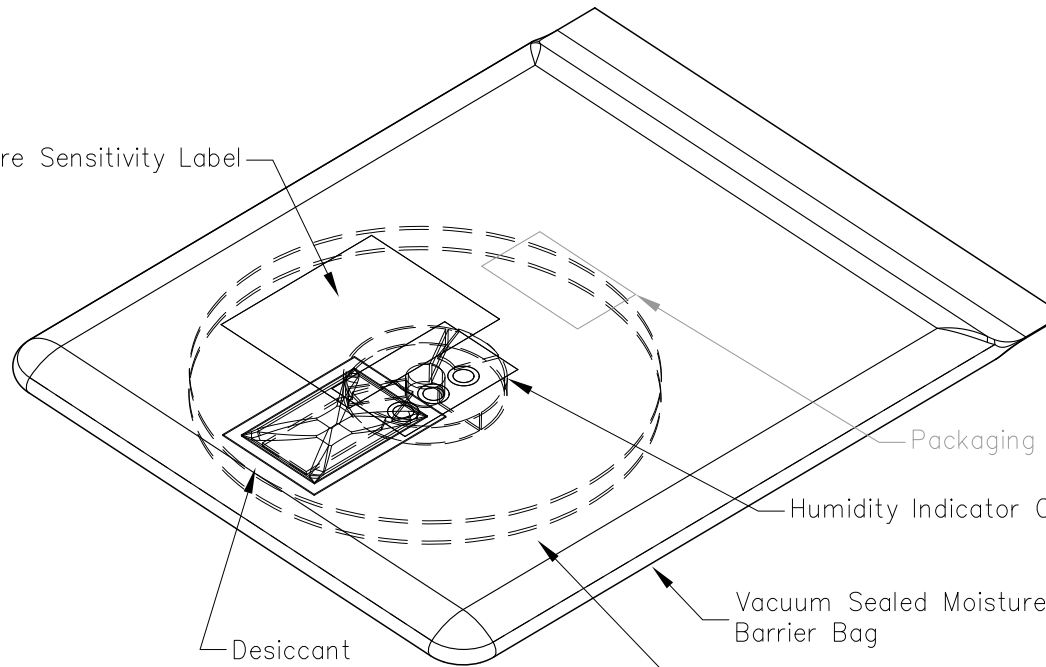
5%	10%	60%
<b>LEVEL 2A-5A PARTS</b>	<b>LEVEL 2 PARTS</b>	
Bake if 10% IS NO BROWN and 5% IS AZURE	Bake Parts if 60% IS NO BROWN	
<b>DOU YEE ENTERPRISES</b>		
<b>BROWN-DRY AXURE-WET</b>	<b>COBALT FREE HUMIDITY INDICATOR CARD</b>	
AVOID METAL CONTACT		
COMPLIES WITH IPC/JEDEC J-STD-033		
H16 5 4 3 2 1		

Humidity Indicator Card

**sensl**  
sense light

**Part#: MicroRA-100XX-MLP**  
**Revision: C1**  
**Lot#: E5678-35**  
**Quantity: 3000**

Sample Packaging Label



Desiccant

Packaging Label

Humidity Indicator Card

Vacuum Sealed Moisture Barrier Bag

Packaging Reel with 3,000 Components on Tape

DATE	19 July 2017	REVISION	A	SCALE:	Shown
SensL Technologies Ltd					Sheet
www.sensl.com					6 of 6
DWG. NO:	SND0218	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
<b>MicroRA-100XX-MLP-C1</b>					
PROJECTION:		<b>sensl</b> sense light			